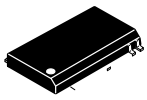
3.3 2/4, 4/ 100 3



SOIC−20 WB
DW SUFFIX
CASE 751D

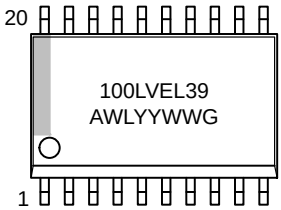
Description

—

µ

Features

MARKING DIAGRAM*



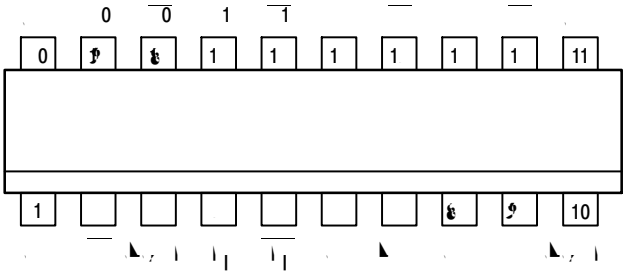
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

Device	Package	Shipping†
MC100LVEL39DWR2G	SOIC−20 WB (Pb-Free)	1000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



Warning: All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Pinout: SOIC−20 WB (Top View)

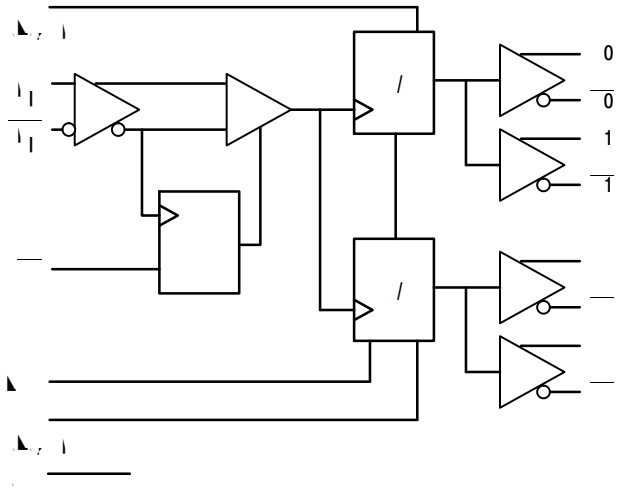


Figure 2. Logic Diagram

Table 1. PIN DESCRIPTION

Column Head	
CLK, $\overline{CLK}$	ECL Diff Clock Inputs
Q_0, Q_1; $\overline{Q_0}$, $\overline{Q_1}$	ECL Diff 2/4 Outputs
Q_2, Q_3; $\overline{Q_2}$, $\overline{Q_3}$	ECL Diff 4/6 Outputs
DIVSELa, DIVSELb	ECL Frequency Select Inputs
$\overline{EN}$	ECL Sync Enable
MR	ECL Master Reset
V_{BB}	Reference Voltage Output
V_{CC}	Positive Supply
V_{EE}	Negative Supply
NC	No Connect

Table 2. FUNCTION TABLE

CLK	$\overline{EN}$	MR	Function
Z	L	L	Divide
ZZ	H	L	Hold Q0−3
X	X	H	Reset Qo−3

Z = Low-to-High Transition
ZZ = High-to-Low Transition
X = Don't Care

DIVSELa	Q_0, Q_1 Outputs
L	Divide by 2
H	Divide by 4
DIVSELb	**Q_2, Q_3 Outputs**
L	Divide by 4
H	Divide by 6

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−8 to 0	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \le V_{CC}$ $V_I \ge V_{EE}$	6 to 0 −6 to 0	V
I_{out}	Output Current	Continuous Surge		50 100	mA
I_{BB}	V_{BB} Sink/Source			0.5	mA
T_A	Operating Temperature Range			−40 to +85	C
T_{stg}	Storage Temperature Range			−65 to +150	C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC−20 WB	90 60	C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC−20 WB	30 to 35	C/W
T_{sol}	Wave Solder (Pb-Free)	< 2 to 3 sec @ 260 C		265	C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. LVPECL DC CHARACTERISTICS (V_{CC} = 3.3 V; V_{EE} = 0.0 V (Note 1))

		−40 C			25 C			85 C			
Symbol	Characteristic	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit
I_{EE}	Power Supply Current		50	59		50	59		54	61	mA
V_{OH}	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V_{OL}	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
V_{IL}	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V_{BB}	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 6) V_{PP} < 500 mV V_{PP} 500 mV	 1.3 1.5		 2.9 2.9	 1.2 1.4		 2.9 2.9	 1.2 1.4		 2.9 2.9	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

Table 5. LVNECL DC CHARACTERISTICS (V_{CC} = 0.0 V; V_{EE} = −3.3 V (Note 4))

Symbol	Characteristic	−40 C			25 C			85 C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		50	59		50	59		54	61	mA
V_{OH}	Output HIGH Voltage (Note 5)	−1085	−1005	−880	−1025	−955	−880	−1025	−955	−880	mV
V_{OL}	Output LOW Voltage (Note 5)	−1830	−1695	−1555	−1810	−1705	−1620	−1810	−1705	−1620	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	−1165		−880	−1165		−880	−1165		−880	mV
V_{IL}	Input LOW Voltage (Single-Ended)	−1810		−1475	−1810		−1475	−1810		−1475	mV
V_{BB}	Output Voltage Reference	−1.38		−1.26	−1.38		−1.26	−1.38		−1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 6) V_{PP} < 500 mV V_{PP} 500 mV	 −2.0 −1.8		 −0.4 −0.4	 −2.1 −1.9		 −0.4 −0.4	 −2.1 −1.9		 −0.4 −0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

4. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary 0.3 V.
5. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
6. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1.0 V.

Table 6. AC CHARACTERISTICS (V_{CC} = 3.3 V; V_{EE} = 0.0 V or V_{CC} = 0.0 V; V_{EE} = −3.3 V (Note 7))

Symbol	Characteristic	−40 C			25 C			85 C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
fmax	Maximum Toggle Frequency	1000			1000			1000			MHz
t_{PLH} t_{PHL}	Propagation Delayed Output CLK to Q (Diff) CLK to Q (S.E.) MR to Q	 850 850 600		 1150 1150 900	 900 900 610		 1200 1200 910	 950 950 630		 1250 1250 930	ps
t_{SKEW}	Within-Device Skew (Note 8) $Q_0 - Q_3$ Part-to-Part $Q_0 - Q_3$ (Diff)			50 200			50 200			50 200	ps
tJITTER	Random CLOCK Jitter (RMS) @ 1000 MHz		2.0	3.0		2.0	3.0		2.0	3.0	ps
t_S	Setup Time $\overline{EN}$ to $\overline{CLK}$ DIVSEL to CLK	 250 400			 250 400			 250 400			ps
t_H	Hold Time $\overline{CLK}$ to $\overline{EN}$ CLK to Div_Sel	 100 150			 100 150			 100 150			ps
V_{PP}	Input Swing (Note 9) CLK	250		1000	250		1000	250		1000	mV
t_{RR}	Reset Recovery Time			100			100			100	ps
t_{PW}	Minimum Pulse Width CLK MR	 500 700			 500 700			 500 700			ps
t_r, t_f	Output Rise/Fall Times Q (20% − 80%)	280		550	280		550	280		550	ps

SOIC−20 WB
CASE 751D−05
ISSUE H

DATE 22 APR 2015